

PACKAGE DIMENSIONS

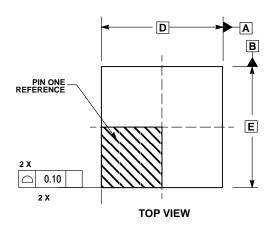


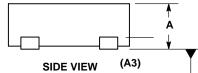


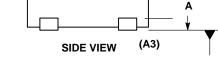
WDFN3 2x2, 1.3P CASE 506AU **ISSUE A**

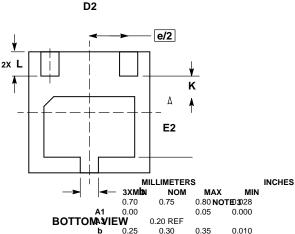
DATE 18 AUG 2016

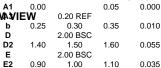
SCALE 4:1











NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.

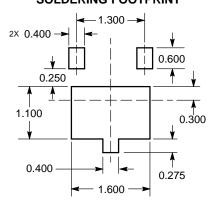
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS
- THE TERMINALS.

					NOM	MAX
					0.030	0.031
						0.002
				0.008 REF		
					0.012	0.014
				0.079 BSC		
					0.059	0.063
				0.079 BSC		
					0.039	0.043
е	1.30 BSC			0.051 BSC		
K	0.35 REF			0.014 REF		
L	0.35	0.40	0.45	0.014	0.016	0.018

GENERIC MARKING DIAGRAM*

XX = Specific Device Code = Date Code

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.